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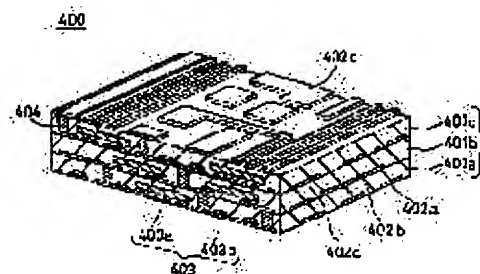
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(54) CIRCUIT PART BUILT-IN MODULE AND MANUFACTURE THEREOF

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a circuit part built-in module, which is high in reliability and where circuit components can be mounted high in density by a method in which an insulating board formed of a mixture containing inorganic filler and thermosetting resin is used.

SOLUTION: A circuit part built-in module comprises an electrically insulating laminated board 401 composed of insulating boards 401a, 401b, and 401c, wiring patterns 402a, 402b, 402c, and 402d formed on the surface and inside of the board 401, a circuit part 403 arranged inside the board 401 and connected to the wiring pattern, and inner vias 404 which electrically connect the wiring patterns 402a, 402b, 402c, and 402d. The insulating boards 401a, 401b, and 401c are formed of a mixture which contains inorganic filler and thermosetting resin.



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